

Procedure file

Basic information	
DEA - Delegated acts procedure	2018/2947(DEA)
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Procedure completed - delegated act enters into force
Supplementing 2008/0240(COD)	
Subject 3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)	

Technical information	
Procedure reference	2018/2947(DEA)
Procedure type	DEA - Delegated acts procedure
Procedure subtype	Examination of delegated act
Stage reached in procedure	Procedure completed - delegated act enters into force
Committee dossier	ENVI/8/15029